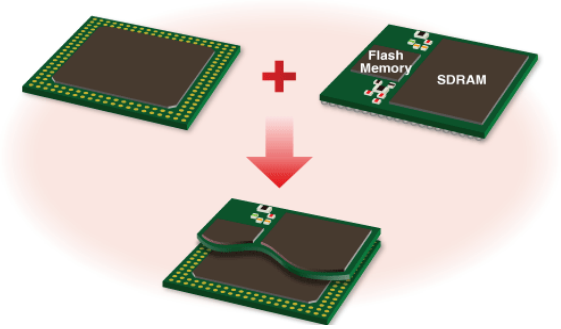
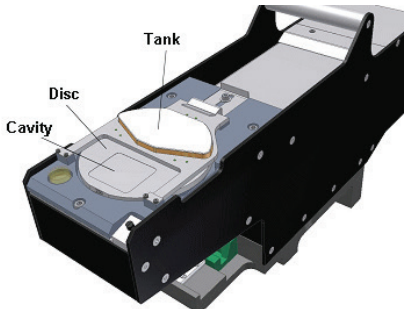
PRODUCT INFORMATION



DESCRIPTION

The Europlacer Rotary Dip Fluxer (E113481) can be used for flip chip placement or PoP applications. It applies flux or solder paste on the component connections and insures a controlled fluid thickness. The component is dipped inside the fluid before its placement.
The fluxer is fitted with a disc where some cavities are machined. Those cavities have different thicknesses, 150µm and 250µm as standard. The disc can be easily swapped with a different one customized according to customer's need.
The "fluxing" is totally integrated in the machine cycle. It is fully 'intelligent' featuring the same intelligence as the other feeders in the Europlacer range.



MACHINE CYCLE

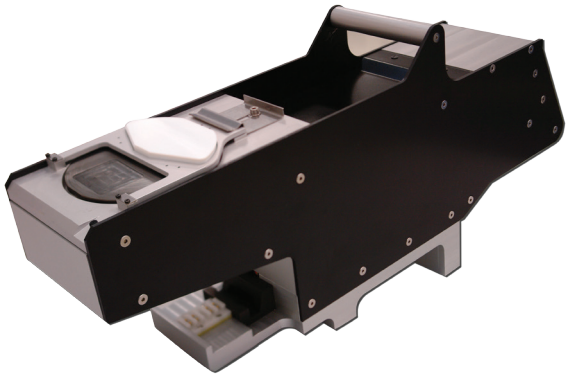
The component dipping operation is fully integrated in the machine placement cycle :

1. Component pick
2. Component analysis (if specified)
3. Displacement over the station / Flux refresh (disc rotation)
4. Dipping
5. Stay in flux for a specified time (adjustable)
6. Lift up
7. Component analysis (if specified)
8. Normal placement cycle.

The level of flux is readjusted at each cycle. Depending on component size, the machine may use the whole surface of the cavity for several components.

POP (PACKAGE ON PACKAGE)

Package on package (PoP) is an integrated circuit packaging method to combine vertically discrete logic and memory ball grid array (BGA) packages. Two or more packages are installed atop each other. This allows higher component density in devices, such as mobile phones, personal digital assistants (PDA), and digital cameras.
PoP assembly process involves a dipping process.



THICKNESS CONTROL PRINCIPLE

The unit is fitted with a removable disc where cavities are machined in. The thickness of these cavities is accurately made (the dimension are determined to meet the customer requirements).
The disc, by rotating, provides a cavity where a component can be dipped. In the same time the second pocket is filled by moving below the tank.